

VERSION WITH MARKINGS TO SHOW CHANGES MADE 09/392,722

IN THE CLAIMS:

Claim 39 has been amended as follows:

39. (Three Times Amended) A method for fabricating an integrated electronic device having an electric connection connecting a first electrode of a first substrate with a second electrode of a second substrate, method comprising the steps of:

forming first and second soldering metal bumps on the surfaces of the first and second electrodes, respectively, wherein a melting temperature of the first soldering metal bump [being] is higher than a melting temperature of the second soldering metal bump;

aligning the first and second soldering metal bumps to each other, and then keeping both in contact with each other; and

heating the first and second soldering metal bumps to melt the second soldering metal bump at a [connection] temperature lower than the melting temperature of the first soldering metal bump [and solidifying] without melting the first soldering metal bump and then cooling down to solidify the second soldering metal to form an electric connection between the first and second electrodes, wherein the first surface of the first electrode is not contacted with molten soldering metal throughout an entire manufacturing process of the integrated electronic device.